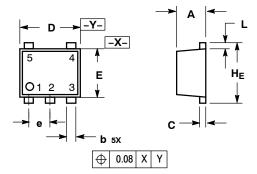


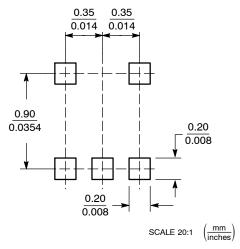
SOT-953 CASE 527AB-01 ISSUE C

DATE 30 JUL 2008

SCALE 4:1



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETERS

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MII	LLIMETE	RS	INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.34	0.42	0.50	0.013	0.017	0.020
b	0.10	0.15	0.20	0.004	0.006	0.008
С	0.05	0.10	0.15	0.002	0.004	0.006
D	0.95	1.00	1.05	0.037	0.039	0.041
E	0.75	0.80	0.85	0.03	0.032	0.034
е	0.35 BSC			0.014 BSC		
L	0.05	0.10	0.15	0.002	0.004	0.006
HE	0.95	1.00	1.05	0.037	0.039	0.041

GENERIC MARKING DIAGRAM*



Χ = Specific Device Code = Month Code

Μ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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NEW STANDARD:		"CONTROLLED C
DESCRIPTION:	SOT-953, 1X1, 0.35P	

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PAGE 2 OF 2

ISSUE	REVISION	DATE	
0	RELEASED FOR PRODUCTION. REQ. BY D. TRUHITTE	17 NOV 2005	
Α	CORRECTED DEVICE MARKING INFORMATION TO REFLECT ONLY ONE CHARACTER FOR DEVICE CODE. REQ. BY D. TRUHITTE.	05 MAY 2008	
В	CHANGED DIMENSION A TO ACCOMODATE PACKAGE HEIGHT FROM 0.34 TO 0.50 MM. REQ. BY S. RAO.	22 MAY 2008	
С	CORRECTED ENGLISH DIMENSIONS FOR PAD SIZES ON SOLDERING FOOT-PRINT FROM 0.08 TO 0.008. REQ. BY D. TRUHITTE.	30 JUL 2008	

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